

Evyap Oleo DTPKFA

(Distilled Topped Palm Kernel Fatty Acid)

Product Code: DNT 200

Product Data Sheet

| CAS No. 90990-15-1 | | EINECS No. 292-776-4 |
|---|--|---|
| Parameter | Unit | Specification |
| Appearance at 40 Deg. C | - | Clear liquid, free from foreign matter. |
| Colour, Lovibond, Max | In 5, ¼" Cell | Y=5.0; R= 0.5 |
| Acid Value | mg KOH/Gm | 246-265 |
| Sap. Value | mg KOH/Gm | 247-266 |
| lodine Value | $Gm I_2 / 100 Gm$ | 14-22 |
| Titre, Min | ° C | 20-28 |
| Fatty Acid Composition | Unit | Specification |
| Up to C 10 C 12 C 14 C 16 C 18 C 18:1 C18:2 Others | % by GC % by GC | 2.0 Max 45 - 58 14 - 20 7 - 12 5.0 Max 12 - 20 4.0 Max 1.0 |

The above chart indicates typical available specifications. Customised specifications are also available.

APPLICATIONS

Preparation of food ingredients, cosmetics and personal care products, surfactant manufacture, soap noodles, industrial application like coatings and fabric softener.

PACKING

Available in standard 180kg HDPE / MS drums, road tankers or bulk ISO container loads. Customised packing size can be made available upon request.

BEST BEFORE

24 months from the date of manufacturing in original containers, stored under standard conditions.

CERTIFICATIONS

This product is Kosher certified by OK Kosher Certification (USA) & Halal certified by JAKIM (MALAYSIA). This product is manufactured in facility certified as per ISO 9001:2015, FSSC 22000, GMP+B2 by Lloyd's Register Quality Assurance and RSPO Supply Chain MB Certification Standard certified by SIRIM (MALAYSIA), Certificate Number: RSPO-SC 00157.

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